

High Performance Microprocessor with Memory Management and Protection

March 1997

Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- Compatible with NMOS 80286/883
- Static CMOS Design for Low Power Operation
 - ICCSB = 5mA Maximum
 - ICCOP = 185mA Maximum (80C286-10/883)
 - ICCOP = 220mA Maximum (80C286-12/883)
- Large Address Space
 - 16 Megabytes Physical
 - 1 Gigabyte Virtual per Task
- Integrated Memory Management, Four-Level Memory Protection and Support for Virtual Memory and Operating Systems
- Two 80C86 Upward Compatible Operating Modes
 - 80C286/883 Real Address Mode
 - Protected Virtual Address Mode
- Compatible with 80287 Numeric Data Co-Processor

Description

The Intersil 80C286/883 is a static CMOS version of the NMOS 80286 microprocessor. The 80C286/883 is an advanced, high-performance microprocessor with specially optimized capabilities for multiple user and multi-tasking systems. The 80C286/883 has built-in memory protection that supports operating system and task isolation as well as program and data privacy within tasks. The 80C286/883 includes memory management capabilities that map 230 (one gigabyte) of virtual address space per task into 2²⁴ bytes (16 megabytes) of physical memory.

The 80C286/883 is upwardly compatible with 80C86 and 80C88 software (the 80C286/883 instruction set is a superset of the 80C86/80C88 instruction set). Using the 80C286/883 real address mode, the 80C286/883 is object code compatible with existing 80C86 and 80C88 software. In protected virtual address mode, the 80C286/883 is source code compatible with 80C86 and 80C88 software but may require upgrading to use virtual address as supported by the 80C286/883's integrated memory management and protection mechanism. Both modes operate at full 80C286/883 performance and execute a superset of the 80C86 and 80C88 instructions.

The 80C286/883 provides special operations to support the efficient implementation and execution of operating systems. For example, one instruction can end execution of one task, save its state, switch to a new task, load its state, and start execution of the new task. The segment-not-present exception and restartable instructions.

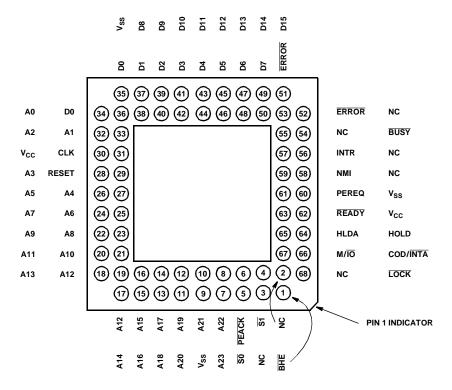
Ordering Information

PACKAGE	TEMP. RANGE	10MHz	12.5MHz	16MHz	20MHz	25MHz	PKG. NO.
68 Pin PGA	0°C to +70°C	-	CG80C286-12	CG80C286-16	CG80C286-20	-	G68.B
	-40°C to +85°C	IG80C286-10	IG80C286-12	-	-	-	G68.B
	-55°C to +125°C	MG80C286-10/883	MG80C286-12/883	-	-	-	G68.B
		5962-9067801MXC	5962-9067802MXC	-	-	-	G68.B

Pinout

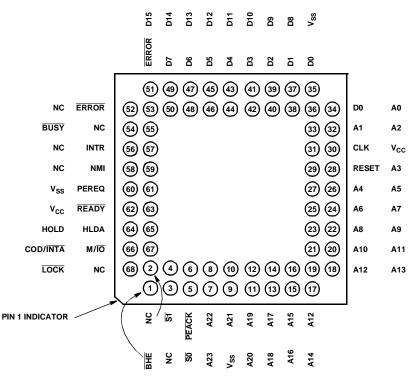
68 LEAD PGA, COMPONENT PAD VIEW

As viewed from underside of the component when mounted on the board.



P.C. BOARD VIEW

As viewed from the component side of the P.C. board.



Absolute Maximum Ratings

Thermal Information

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Operating Conditions

Operating Voltage Range +4.5V to +5.5V	Input RISE and FALL Time (From 0.8V to 2.0V
Operating Temperature Range55°C to +125°C	80C286-10/883
System Clock (CLK) RISE Time (From 1.0V to 3.6V 8ns (Max)	80C286-12/883 8ns (Max)
System Clock (CLK) FALL Time (from 3.6V to 1.0V) 8ns (Max)	

TABLE 1. 80C286/883 D.C. ELECTRICAL PERFORMANCE SPECIFICATIONS

Device Guaranteed and 100% Tested

			GROUP A		LIN	/IITS	
PARAMETER	SYMBOL	CONDITIONS	SUB- GROUPS	TEMPERATURE	MIN	MAX	UNITS
Input LOW Voltage	V_{IL}	V _{CC} = 4.5V	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	-0.5	0.8	V
Input HIGH Voltage	V_{IH}	V _{CC} = 5.5V	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	2.0	V _{CC} +0.5	V
CLK Input LOW Voltage	V _{ILC}	V _{CC} = 4.5V	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	-0.5	1.0	V
CLK Input HIGH Voltage	V_{IHC}	V _{CC} = 5.5V	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	3.6	V _{CC} +0.5	V
Output LOW Voltage	V _{OL}	$I_{OL} = 2.0 \text{mA}, V_{CC} = 4.5 \text{V}$	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	-	0.4	V
Output HIGH Voltage	V _{OH}	$I_{OH} = -2.0 \text{mA}, V_{CC} = 4.5 \text{V}$	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	3.0	-	V
		$I_{OH} = -100 \mu A, V_{CC} = 4.5 V$			V _{CC} -0.4	-	V
Input Leakage Current	I _I	$V_{IN} = GND \text{ or } V_{CC},$ $V_{CC} = 5.5V,$ Pins 29, 31, 57, 59, 61, 63-64	1, 2, 3	-55°C ≤ T _A ≤ +125°C	-10	10	μА
Input Sustaining Current LOW	I _{BHL}	V _{CC} = 4.5V and 5.5V, V _{IN} = 1.0V, Note 1	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	38	200	μА
Input Sustaining Current HIGH	I _{BHH}	V _{CC} = 4.5V and 5.5V, V _{IN} = 3.0V, Note 2	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	-50	-400	μΑ
Input Sustaining Current on BUSY and ERROR Pins	I _{SH}	V_{CC} = 4.5V and 5.5V V_{IN} = GND, Note 5	1, 2, 3	-55°C ≤ T _A ≤ +125°C	-30	-500	μΑ
Output Leakage Current	I _O	$V_O = \text{GND or } V_{CC}$ $V_{CC} = 5.5V$, Pins 1, 7-8, 10-28, 32-34	1, 2, 3	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$	-10	10	μΑ
Active Power Supply	I _{CCOP}	80C286-10/883, Note 4	1, 2, 3	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$	-	185	mA
Current		80C286-12/883, Note 4			-	220	mA
Standby Power Supply Current	Іссѕв	V _{CC} = 5.5V, Note 3	1, 2, 3	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	-	5	mA

NOTES:

- 2. I_{BHL} should be measured after lowering V_{IN} to GND and then raising to 1.0V on the following pins: 36-51, 66, 67.
- 3. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering to 3.0V on the following pins: 4-6, 36-51, 66-68.
- 4. I_{CCSB} should be tested with the clock stopped in phase two of the processor clock cycle. $V_{IN} = V_{CC}$ or GND, $V_{CC} = 5.5V$, outputs unloaded.
- 5. I_{CCOP} measured at 10MHz for the 80C286-10/883 and 12.5MHz for the 80C286-12/883. V_{IN} = 2.4V or 0.4V, V_{CC} = 5.5V, outputs unloaded.
- 6. I_{SH} should be measured after raising V_{IN} to V_{CC} and then lowering to 0V on pins 53 and 54.

TABLE 2. 80C286/883 AC ELECTRICAL PERFORMANCE SPECIFICATIONS

AC Timings are Referenced to 0.8V and 2.0V Points of the Signals as Illustrated in Datasheet Waveforms, Unless Otherwise Noted. Device Guaranteed and 100% Tested.

						80C28	36/883		
			ODOUD A		101	ИHz	12.5	MHz	
PARAMETER	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	MIN	MAX	MIN	MAX	UNITS
System Clock (CLK) Period	1	V _{CC} = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	50	-	40	-	ns
System Clock (CLK) Low Time	2	V _{CC} = 4.5V and 5.5V at 1.0V	9, 10, 11	-55°C ≤T _A ≤ +125°C	12	-	11	-	ns
System Clock (CLK) High Time	3	V _{CC} = 4.5V and 5.5V at 3.6V	9, 10, 11	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	16	-	13	-	ns
Asynchronous Inputs SETUP Time (Note 1)	4	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤ T _A ≤ +125°C	20	-	15	-	ns
Asynchronous Inputs HOLD Time (Note 1)	5	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤ T _A ≤ +125°C	20	-	15	-	ns
RESET SETUP Time	6	V _{CC} = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	19	-	10	-	ns
RESET HOLD Time	7	V _{CC} = 4.5V and 5.5V	9, 10, 11	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	0	-	0	-	ns
Read Data SETUP Time	8	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤ T _A ≤ +125°C	8	-	5	-	ns
Read Data HOLD Time	9	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤ T _A ≤ +125°C	4	-	4	-	ns
READY SETUP Time	10	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤ T _A ≤ +125°C	26	-	20	-	ns
READY HOLD Time	11	V _{CC} = 4.5V and 5.5V	9, 10, 11	-55°C ≤T _A ≤ +125°C	25	-	20	-	ns
Status/PEACK Active Delay, (Note 4)	12A	$V_{CC} = 4.5V$ and 5.5V, $C_L = 100pF$ $I_L = 2mA $	9, 10, 11	-55°C ≤ T _A ≤ +125°C	1	22	1	21	ns
Status/PEACK Inactive Delay (Note 3)	12B	$V_{CC} = 4.5V$ and 5.5V, $C_L = 100pF$ $I_L = 2mA $	9, 10, 11	-55°C ≤ T _A ≤ +125°C	1	30	1	24	ns
Address Valid Delay (Note 2)	13	$V_{CC} = 4.5V$ and $5.5V$, $C_L = 100pF$ $I_L = 2mA $	9, 10, 11	-55°C ≤ T _A ≤ +125°C	1	35	1	32	ns
Write Data Valid Delay, (Note 2)	14	V_{CC} = 4.5V and 5.5V, C_L = 100pF I_L = 2mA	9, 10, 11	-55°C ≤ T _A ≤ +125°C	0	40	0	31	ns

TABLE 2. 80C286/883 AC ELECTRICAL PERFORMANCE SPECIFICATIONS (Continued)

AC Timings are Referenced to 0.8V and 2.0V Points of the Signals as Illustrated in Datasheet Waveforms, Unless Otherwise Noted. Device Guaranteed and 100% Tested.

						80C28	6/883		
			GROUP A		101	ИHz	12.5	MHz	
PARAMETER	SYMBOL	CONDITIONS	SUBGROUPS	TEMPERATURE	MIN	MAX	MIN	MAX	UNITS
HLDA Valid Delay (Note 5)	15	$V_{CC} = 4.5V$ and 5.5V, $C_L = 100pF$ $IL = 2mA $	9, 10, 11	-55°C ≤ T _A ≤ +125°C	0	47	0	25	ns

NOTES:

- 1. Asynchronous inputs are INTR, NMI, HOLD, PEREQ, ERROR, and BUSY. This specification is given only for testing purposes, to assure recognition at a specific CLK edge.
- 2. Delay from 1.0V on the CLK to 0.8V or 2.0V.
- 3. Delay from 1.0V on the CLK to 0.8V for Min (HOLD time) and to 2.0V for Max (inactive delay).
- 4. Delay from 1.0V on the CLK to 2.0V for Min (HOLD time) and to 0.8V for Max (active delay).
- 5. Delay from 1.0V on the CLK to 2.0V.

TABLE 3. 80C286/883 ELECTRICAL PERFORMANCE SPECIFICATIONS

						80C28	36/883		
					101	ИHz	12.5	MHz	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	MIN	MAX	UNITS
CLK Input Capacitance	C _{CLK}	FREQ = 1MHz	5	$T_A = +25^{\circ}C$	-	10	-	10	pF
Other Input Capacitance	C _{IN}	FREQ = 1MH	5	T _A = +25°C	-	10	-	10	pF
I/O Capacitance	C _{I/O}	FREQ = 1MH	5	T _A = +25°C	-	10	-	10	pF
Address/Status/Data Float Delay	15		1, 3, 4, 5	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$	0	47	0	32	ns
Address Valid to Status SETUP Time	19	I _L = 2.0mA	1, 2, 5	$-55^{\circ}C \le T_{A} \le +125^{\circ}C$	27	-	20	-	ns

NOTES:

- 1. Output Load: $C_L = 100pF$.
- 2. Delay measured from address either reaching 0.8V or 2.0V (valid) to status going active reaching 0.8V or status going inactive reaching 2.0V.
- 3. Delay from 1.0V on the CLK to Float (no current drive) condition.
- 4. $I_L = -6mA$ (V_{OH} to Float), $I_L = 8mA$ (V_{OL} to Float).
- 5. The parameters listed in Table 3 are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design and after major process and/or design changes.

TABLE 4. APPLICABLE SUBGROUPS

CONFORMANCE GROUPS	METHOD	SUBGROUPS
Initial Test	100%/5004	-
Interim Test	100%/5004	1, 7, 9
PDA	100%	1
Final Test	100%	2, 3, 8A, 8B, 10, 11
Group A	-	1, 2, 3, 7, 8A, 8B, 9, 10, 11
Group C & D	Samples/5005	1, 7, 9

AC Electrical Specifications 82C284 and 82C288 Timing Specifications Are Given For Reference Only, And No Guarantee is Implied.

82C284 Timing

		101	ИHz	12.5MHz	2		
SYMBOL	PARAMETER	MIN	MAX	MIN	MAX	UNIT	TEST CONDITION
TIMING REQU	IREMENTS						
11	SRDY/SRDYEN Setup Time	15	-	15	-	ns	
12	SRDY/SRDYEN Hold Time	2	-	2	-	ns	
13	ARDY/ARDYEN Setup Time	5	-	5	-	ns	(Note 1)
14	ARDY/ARDYEN Hold Time	30	-	25	-	ns	(Note 1)
TIMING RESP	ONSES						
19	PCLK Delay	0	20	0	16	ns	$C_L = 75pF$, $I_{OL} = 5mA$, $I_{OH} = -1mA$

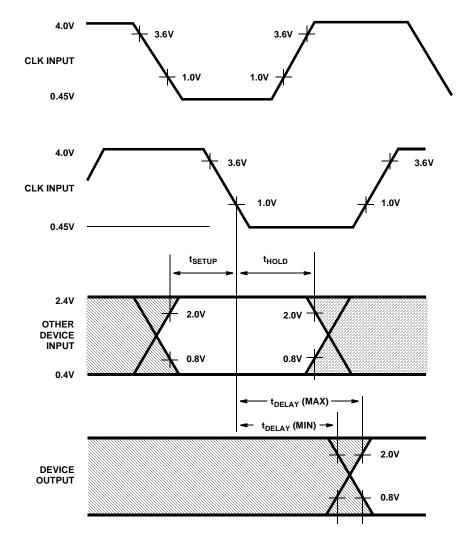
NOTE:

82C288 Timing

		10	ИНz	12.5	MHz		
SYMBOL	PARAMETER	MIN	MAX	MIN	MAX	UNIT	TEST CONDITION
TIMING RE	QUIREMENTS						
12	CMDLY Setup Time	15	-	15	-	ns	
13	CMDLY Hold Time	1	-	1	-	ns	
TIMING RE	SPONSES						
16	ALE Active Delay	1	16	1	16	ns	
17	ALE Inactive Delay	-	19	-	19	ns	
19	DT/R Read Active Delay	-	23	-	23	ns	C _L = 150pF
20	DEN Read Active Delay	0	21	0	21	ns	I _{OL} = 16mA Max
21	DEN Read Inactive Delay	3	23	3	21	ns	I _{OH} = -1mA Max
22	DT/R Read Inactive Delay	5	24	5	18	ns	
23	DEN Write Active Delay	-	23	-	23	ns	
24	DEN Write Inactive Delay	3	23	3	23	ns	
29	Command Active Delay from CLK	3	21	3	21	ns	C _L = 300pF
30	Command Inactive Delay from CLK	3	20	3	20	ns	I _{OL} = 32mA Max

^{1.} These times are given for testing purposes to ensure a predetermined action.

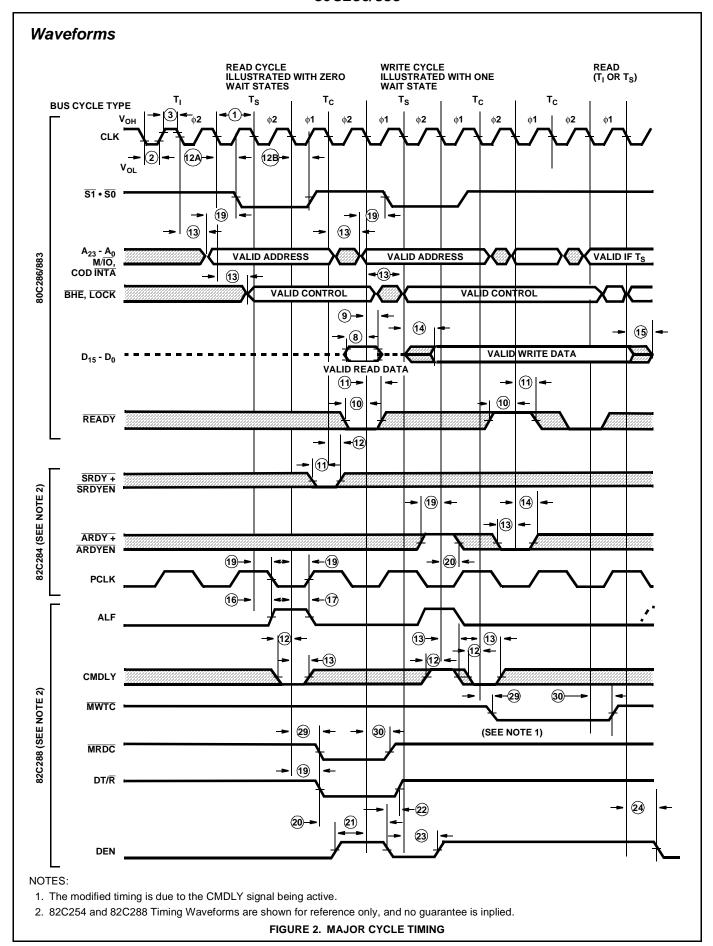
AC Specifications



NOTE:

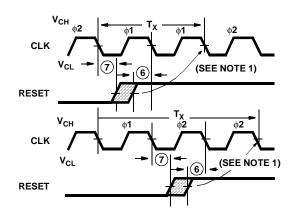
1. For AC testing, input rise and fall times are driven at 1ns per volt.

FIGURE 1. AC DRIVE AND MEASURE POINTS - CLK INPUT



Waveforms (Continued)

BUS CYCLE TYPE CLK VCL PCLK (SEE NOTE 1) INTR, NMI HOLD, PEREQ (SEE NOTE 2) ERROR, BUSY (SEE NOTE 2)



NOTES:

- PCLK indicates which processor cycle phase will occur on the next CLK. PCLK may not indicate the correct phase until the first cycle is performed.
- 2. These inputs are asynchronous. The setup and hold times shown assure recognition for testing purposes.

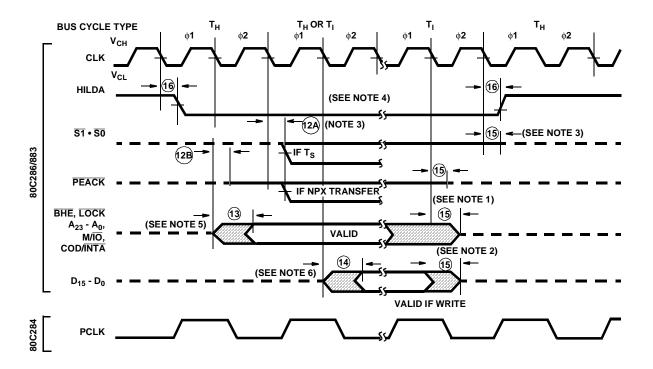
FIGURE 3. 80C286/883 ASYNCHRONOUS INPUT SIGNAL TIMING

NOTE:

1. When RESET meets the setup time shown, the next CLK will start or repeat $\phi 1$ of a processor cycle.

FIGURE 4. 80C286/883 RESET INPUT TIMING AND SUBSE-QUENT PROCESSOR CYCLE PHASE

Waveforms (Continued)

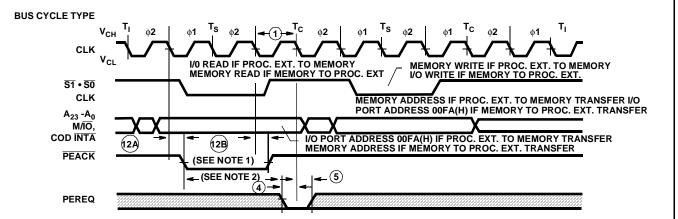


NOTES:

- 1. These signals may not be driven by the 80C286/883 during the time shown. The worst case in terms of latest float time is shown.
- 2. The data bus will be driven as shown if the last cycle before T_I in the diagram was a write T_C.
- 3. The 80C286/883 puts its status pins in a high impedance logic one state during T_H.
- 4. For HOLD request set up to HLDA, refer to Figure 8.
- 5. \overline{BHE} and \overline{LOCK} are driven at this time but will not become valid until T_S.
- 6. The data bus will remain in a high impedance state if a read cycle is performed.

FIGURE 5. EXITING AND ENTERING HOLD

Waveforms (Continued)

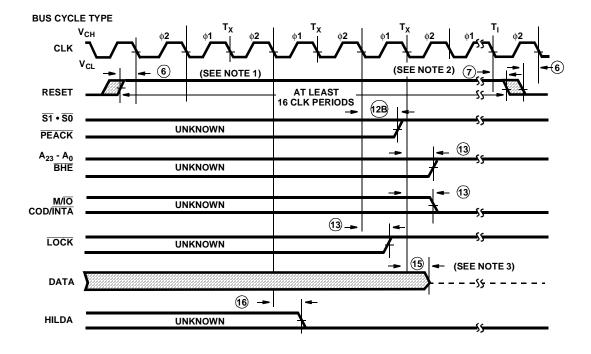


NOTES:

- 1. PEACK always goes active during the first bus operation of a processor extension data operand transfer sequence. The first bus operation will be either a memory read at operand address or I/O read at port address 00FA(H).
- 2. To prevent a second processor extension data operand transfer, the worst case maximum time (shown above) is 3 x 1 12A_{MAX} -(4)_{MIN}

 The actual, configuration dependent, maximum time is: 3 x 1 12A_{MAX} (4)_{MIN} +N x 2 x (1). N is the number of extra T_C states added to either the first or second bus operation of the processor extension data operand transfer sequence.

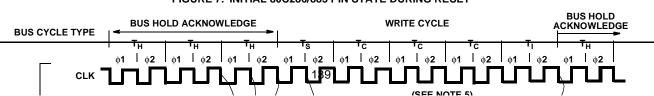
FIGURE 6. 80C286/883 PEREQ/PEACK TIMING FOR ONE TRANSFER ONLY



NOTES:

- 1. Setup time for RESET ↑ may be violated with the consideration that φ1 of the processor clock may begin one system CLK period later.
- 2. Setup and hold times for RESET ↓ must be met for proper operation, but RESET ↓ may occur during \$\phi\$1 or \$\phi 2\$.
- 3. The data bus is only guaranteed to be in a high impedance state at the time shown.

FIGURE 7. INITIAL 80C286/883 PIN STATE DURING RESET



Die Characteristics

DIE DIMENSIONS: 286 x 283 x 19 ±1 mils

METALLIZATION:

Type: Si-Al Thickness: 8kÅ **GLASSIVATION:**

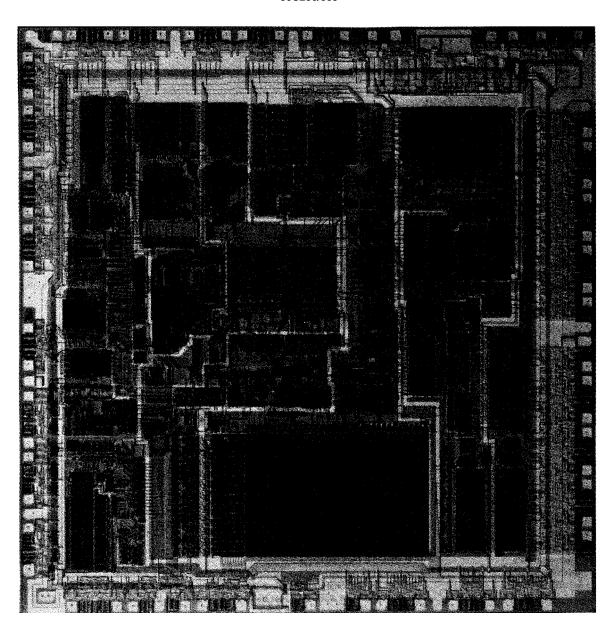
Type: Nitrox Thickness: 10kÅ

WORST CASE CURRENT DENSITY: 2 X 10⁵A/cm²

LEAD TEMPERATURE: (10s Soldering): ≤ 300°C

Metallization Mask Layout

80C286/883



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